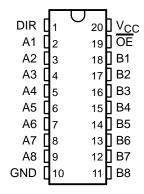
SN54LVT245B, SN74LVT245B 3.3-V ABT OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

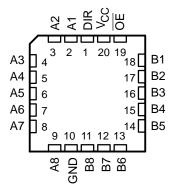
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- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low-Static Power Dissipation
- High-Impedance State During Power Up and Power Down
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Power Off Disables Inputs/Outputs, Permitting Live Insertion
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Packages, and Ceramic (J) DIPs

SN54LVT245B . . . J OR W PACKAGE SN74LVT245B . . . DB, DW, OR PW PACKAGE (TOP VIEW)



SN54LVT245B . . . FK PACKAGE (TOP VIEW)



description

These octal bus transceivers are designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

These devices are designed for asynchronous communication between data buses. They transmit data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (OE) input can be used to disable the devices so the buses are effectively isolated.

When V_{CC} is between 0 and 1.5 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVT245B is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed circuit board area.

The SN54LVT245B is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74LVT245B is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

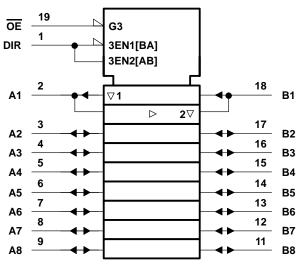


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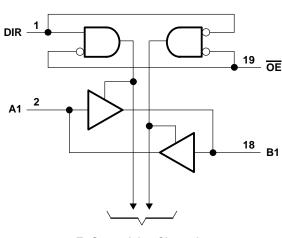
FUNCTION TABLE

INP	UTS	OPERATION					
OE	DIR	OPERATION					
L	L	B data to A bus					
L	Н	A data to B bus					
Н	Χ	Isolation					

logic symbol[†]



logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	–0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V _O (see Note 1)	–0.5 V to 7 V
Current into any output in the low state, IO: SN54LVT245B	96 mA
SN74LVT245B	128 mA
Current into any output in the high state, IO (see Note 2): SN54LVT245B	48 mA
SN74LVT245B	64 mA
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	
Maximum power dissipation at T _A = 55°C (in still air) (see Note 3): DB package	0.6 W
DW package	1.6 W
PW package	0.7 W
Storage temperature range, T _{stg}	–65°C to 150°C

^{\$\}frac{1}{2}\$ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 - 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the Package Thermal Considerations application note in the ABT Advanced BiCMOS Technology Data Book.



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

recommended operating conditions (see Note 4)

						SN74LVT245B	
		MIN	MAX	MIN	MAX	UNIT	
Vcc	Supply voltage	2.7	3.6	2.7	3.6	V	
VIH	High-level input voltage	2	EN	2		V	
V_{IL}	Low-level input voltage		0.8		0.8	V	
VI	Input voltage		5.5		5.5	V	
Іон	High-level output current	Ç	-24		-32	mA	
loL	Low-level output current	200	48		64	mA	
Δt/Δν	Input transition rise or fall rate	Outputs enabled	BA	10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V
T _A	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

SN54LVT245B, SN74LVT245B 3.3-V ABT OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	_	SN	54LVT24	15B	SN	UNIT					
PARAMETER		MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNII			
VIK	$V_{CC} = 2.7 \text{ V},$	I _I = -18 mA				-1.2			-1.2	V	
	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ $I_{OH} = -100 \mu\text{A}$			VCC-0	0.2		V _{CC} -0.2				
^V ОН	$V_{CC} = 2.7 \text{ V},$	$I_{OH} = -8 \text{ mA}$	2.4			2.4			V		
	VCC = 3 V	$I_{OH} = -24 \text{ mA}$	2						· I		
	VCC = 3 V	$I_{OH} = -32 \text{ mA}$				2					
	V _{CC} = 2.7 V	$I_{OL} = 100 \mu A$				0.2			0.2		
	VCC = 2.7 V	$I_{OL} = 24 \text{ mA}$			0.5	0.5					
V _{OL}		$I_{OL} = 16 \text{ mA}$			0.4				0.4	V	
VOL	V00 = 3 V	$I_{OL} = 32 \text{ mA}$		0.5			0.5				
	V _{CC} = 3 V	$I_{OL} = 48 \text{ mA}$	0.55								
		$I_{OL} = 64 \text{ mA}$	\$			0.55					
	$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND	Control inputs		±1			±1			
	$V_{CC} = 0 \text{ or } 3.6 \text{ V}$	V _I = 5.5 V			10			10			
IJ	V _{CC} = 3.6 V	V _I = 5.5 V			20			20			
		$V_I = V_{CC}$	A or B ports‡		1			1			
		V _I = 0		– 5			-5				
l _{off}	$V_{CC} = 0$,	V_{I} or $V_{O} = 0$ to 4.5	V	Q					±100	μΑ	
IOZPU [§]	$V_{CC} = 0 \text{ to } 1.5 \text{ V},$	$V_0 = 0.5 \text{ V to 3 V},$	OE = X			±100			±100	μΑ	
IOZPD§	$V_{CC} = 1.5 \text{ V to } 0,$	$V_0 = 0.5 \text{ V to 3 V},$	OE = X			±100			±100	μΑ	
lcc	V _{CC} = 3.6 V,	I _O = 0,	Outputs high						0.19		
			Outputs low	W		5			5	mA	
	V _I = V _{CC} or GND		Outputs disabled			0.19			0.19	112	
ΔI _{CC} ¶	$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$ Other inputs at V_{CC} o			0.2			0.2	mA			
C _i	V _I = 3 V or 0				4			4		pF	
C _{io}	V _O = 3 V or 0				9			9		pF	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] Unused terminals are at V_{CC} or GND.

[§] This parameter is specified by characterization but is not tested.

[¶]This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

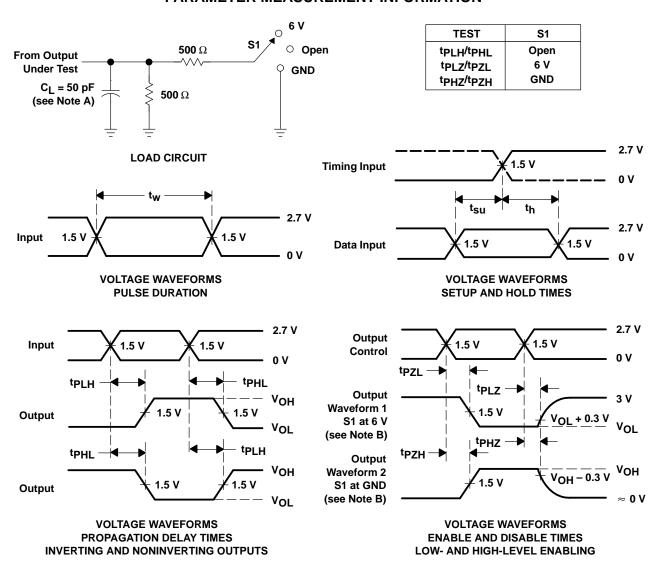
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switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

		TO (OUTPUT)	SN54LVT245B				SN74LVT245B						
PARAMETER	FROM (INPUT)		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT	
			MIN	MAX	MIN	MAX	MIN	TYP [†]	MAX	MIN	MAX		
t _{PLH}	A or B	B or A	1.1	3.7		4.2	1.2	2.3	3.5		4	ns	
^t PHL		BOIA	1.1	3.7	136	4.2	1.2	2.1	3.5		4		
^t PZH	ŌĒ		A or B	1.2	5.7	\d'_	7.4	1.3	3.2	5.5		7.1	ns
t _{PZL}		AUIB	1.6	5.7	ر '	6.8	1.7	3.4	5.5		6.5	115	
^t PHZ	ŌĒ	OE A or B	2.1	6.2		6.8	2.2	3.5	5.9		6.5	ns	
t _{PLZ}			2.1	5.3		5.5	2.2	3.4	5		5.1	115	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_0 = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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